

Industry First Low Capacitance ESD Protection Arrays w/Backdrive Protection

CM1223

Features

- Two, four, and eight channels of ESD protection with integrated backdrive protection on all lines
- Provides ESD protection to IEC61000-4-2 Level 4:
- ±8kV contact discharge
 - ±15kV air discharge
- Low channel input capacitance of 1.0pF (typical)
- Minimal capacitance change with temperature and voltage
- Channel I/O to GND capacitance difference of 0.02pF typical is ideal for differential signals
- Mutual capacitance between signal pin and adjacent signal pin at 0.11pF (typical)
- Zener diode protects supply rail and eliminates the need for external bypass capacitors
- Pin compatible with CM1213-02, -04, and -08
- Each I/O pin can withstand over 1000 ESD strikes*
- Available in SOT, and MSOP packages
- RoHS-compliant, lead-free packaging

Applications

- USB2.0 ports at 480Mbps in desktop PCs, notebooks and peripherals
- IEEE1394 Firewire® ports at 400Mbps / 800Mbps
- DVI ports, HDMI ports in notebooks, set top boxes, digital TVs, LCD displays
- UDI and display ports
- Serial ATA ports in desktop PCs and hard disk drives
- PCI Express ports
- General purpose high-speed data line ESD protection

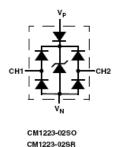
Product Description

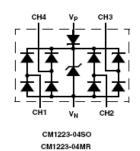
The CM1223 family of diode arrays are designed to provide ESD protection for electronic components or subsystems requiring minimal capacitive loading. These devices are ideal for protecting systems with high data and clock rates or for circuits requiring low capacitive loading. Each ESD channel consists of a pair of diodes in series, which steer the positive or negative ESD current pulse to either the positive (V_P) or negative (V_N) supply rail. A Zener diode is embedded between $V_{\scriptscriptstyle P}$ and $V_{\scriptscriptstyle N}$, to absorb positive ESD strikes and provide ESD protection for the $V_{\scriptscriptstyle P}$ rail. An additional diode is integrated to serve as backdrive current protection. The CM1223 protects against ESD pulses up to ±8kV per the IEC 61000-4-2 standard. In addition, all pins are protected from contact discharges of greater than ±15kV as outlined by the MIL-STD-883D (Method 3015) specification for Human Body Model (HBM) ESD.

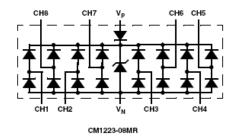
These devices are particularly well-suited for protecting systems using high-speed ports such as USB2.0, IEEE1394 (Firewire®, iLink™), serial ATA, DVI, HDMI and corresponding ports in removable storage, digital camcorders, DVD-RW drives, as well as other applications where extremely low loading capacitance with ESD protection are required in a small package footprint.

The CM1223 family of devices are manufactured with RoHS-compliant, lead-free packaging.

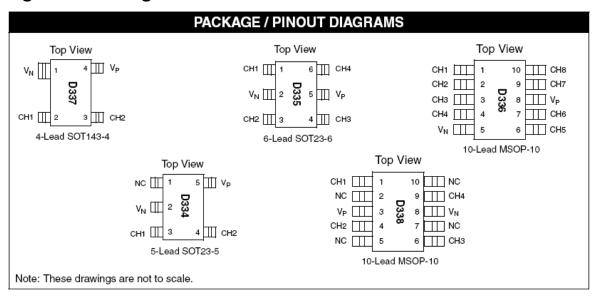
Block Diagram







Package/Pinout Diagrams



CM1223

Pin Configuration

	2-CHANNEL, 4-LEAD SOT143-4 PACKAGE					
PIN	NAME	TYPE	PIN			
1	V _N	GND	Negative voltage supply rail			
2	CH1	I/O	ESD Channel			
3	CH2	I/O	ESD Channel			
4	$V_{_{P}}$	PWR	Positive voltage supply rail			
2-CHANNEL, 5-LEAD SOT23-5 PACKAGE						
PIN	NAME	TYPE	DESCRIPTION			
1	NC		No connect			
2	$V_{_{\rm N}}$	GND	Negative voltage supply rail			
3	CH1	I/O	ESD Channel			
4	CH2	I/O	ESD Channel			
5	V _P	PWR	Positive voltage supply rail			
	4	CHANNEL, 6-I	LEAD SOT23-6 PACKAGE			
PIN	NAME	TYPE	DESCRIPTION			
1	CH1	I/O	ESD Channel			
2	$V_{_{\rm N}}$	GND	Negative voltage supply rail			
3	CH2	I/O	ESD Channel			
4	CH3	I/O	ESD Channel			
5	$V_{_{P}}$	PWR	Positive voltage supply rail			
6	CH4	I/O	ESD Channel			

	4-0	CHANNEL, 10-	LEAD MSOP-10 PACKAGE
PIN	NAME	TYPE	DESCRIPTION
1	CH1	I/O	ESD Channel
2	NC		No connect
3	V _P	PWR	Positive voltage supply rail
4	CH2	I/O	ESD Channel
5	NC		No connect
6	CH3	I/O	ESD Channel
7	NC		No connect
8	V _N	GND	Negative voltage supply rail
9	CH4	I/O	ESD Channel
10	NC		No connect
	8-0	CHANNEL, 10-	LEAD MSOP-10 PACKAGE
PIN	NAME	TYPE	DESCRIPTION
1			
'	CH1	I/O	ESD Channel
2	CH1 CH2	I/O	ESD Channel ESD Channel
2	CH2	I/O	ESD Channel
2	CH2 CH3	I/O I/O	ESD Channel ESD Channel
3 4	CH2 CH3 CH4	I/O I/O	ESD Channel ESD Channel ESD Channel
2 3 4 5	CH2 CH3 CH4 V _N	I/O I/O I/O GND	ESD Channel ESD Channel ESD Channel Negative voltage supply rail
2 3 4 5	CH2 CH3 CH4 V _N CH5	I/O I/O I/O GND I/O	ESD Channel ESD Channel ESD Channel Negative voltage supply rail ESD Channel
2 3 4 5 6	CH2 CH3 CH4 V _N CH5 CH6	I/O I/O I/O GND I/O I/O	ESD Channel ESD Channel ESD Channel Negative voltage supply rail ESD Channel ESD Channel

Ordering Information

PART NUMBERING INFORMATION							
# of Channels	Ordering Part Number ¹	Part Marking					
2	5	SOT23-5	CM1223-02SO	D334			
2	4	SOT143-4	CM1223-02SR	D337			
4	6	SOT23-6	CM1223-04SO	D335			
4	10	10 MSOP-10 CM1223-04MR		D338			
8	10	MSOP-10	CM1223-08MR	D336			

Note 1: Parts are shipped in Tape and Reel form unless otherwise specified.

Specifications

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	RATING	UNITS			
Operating Supply Voltage (V _P - V _N)	6.0	V			
Operating Temperature Range	-40 to +85	°C			
Storage Temperature Range	-65 to +150	°C			
DC Voltage at any channel input	$(V_{N} - 0.5)$ to $(V_{P} + 0.5)$	V			

STANDARD OPERATING CONDITIONS						
PARAMETER	RATING	UNITS				
Operating Temperature Range	-40 to +85	°C				
Package Power Rating SOT143-4 Package (CM1223-02SR) SOT23-5 Package (CM1223-02SO) SOT23-6 Package (CM1223-04SO) MSOP-10 Package (CM1223-04MR) MSOP-10 Package (CM1223-08MR)	225 225 225 400 400	mW mW mW mW				

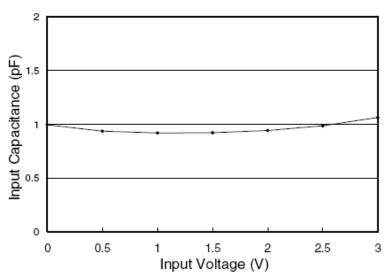
	ELECTRICAL OF	PERATING CHARACTERISTICS	S (SEE NOT	E 1)		
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
V _P	Operating Supply Voltage (V _P -V _N)			3.3	5.5	V
I _P	Operating Supply Current	$(V_{P}-V_{N})=3.3V$			8.0	μΑ
V _{SCL}	Signal Clamp Voltage Positive Transients Negative Transients	I _F = 8mA; T _A =25 ℃	6.7 0.60	8.2 0.80		V V
I _{LEAK}	Channel Leakage Current	$T_A = 25 ^{\circ}\text{C}; V_P = 5V, V_N = 0V$		±0.1	±1.0	μΑ
C _{IN}	Channel Input Capacitance	At 1 MHz, V _P =3.3V, V _N =0V, V _{IN} =1.65V		1.0	1.5	pF
$\Delta C_{\scriptscriptstyleIN}$	Channel Input Capacitance Matching	At 1 MHz, $V_p=3.3V$, $V_N=0V$, $V_{IN}=1.65V$		0.02		pF
C _{MUTUAL}	Mutual Capacitance between signal pin and adjacent signal pin	At 1 MHz, V _p =3.3V, V _N =0V, V _{IN} =1.65V		0.11		pF
V _{ESD}	ESD Protection Peak Discharge Voltage at any channel input, in system a) Contact discharge per IEC 61000-4-2 standard b) Human Body Model, MIL-STD-883, Method 3015	$T_A=25$ °C; Notes 3 and 4 $T_A=25$ °C; Notes 2 and 4	±8 ±15			kV kV
V _{CL}	Channel Clamp Voltage Positive Transients Negative Transients	$T_A = 25 ^{\circ}\text{C}$, $I_{PP} = 1 ^{\circ}\text{A}$, $t_P = 8/20 ^{\circ}\text{\mu S}$; Note 4		+8.8 -1.4		V
$R_{\scriptscriptstyleDYN}$	Dynamic Resistance Positive Transients Negative Transients	$T_A=25^{\circ}\text{C}$, $I_{PP}=1\text{A}$, $t_P=8/20\mu\text{S}$ Any I/O pin to Ground; Note 4		0.7 0.4		Ω

Note 1: All parameters specified at $T_{\rm A}$ = -40 °C to +85 °C unless otherwise noted.

Note 2: Human Body Model per MIL-STD-883, Method 3015, $C_{Discharge} = 100pF$, $R_{Discharge} = 1.5K\Omega$, $V_p = 3.3V$, $V_p = 3$

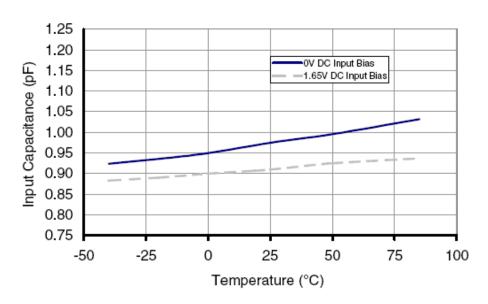
Performance Information

Input Channel Capacitance Performance Curves



Typical Variation of CIN vs. VIN

(f=1MHz, V_P = 3.3V, V_N = 0V, 0.1 μF chip capacitor between V_P and $V_{N_{\star}}$ 25°C)



Typical Variation of C_{IN} vs. Temp

(f=1MHz, V_{IN} =30mV, V_P = 3.3V, V_N = 0V, 0.1 μF chip capacitor between V_P and V_N)

Performance Information (Cont'd)

Typical Filter Performance (nominal conditions unless specified otherwise, 50 Ohm Environment)

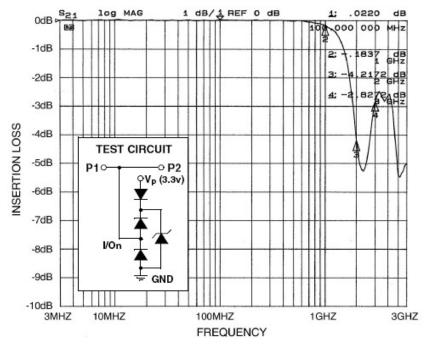


Figure 1. Insertion Loss (S21) VS. Frequency (0V DC Bias, V_p=3.3V, MSOP-8 Package)

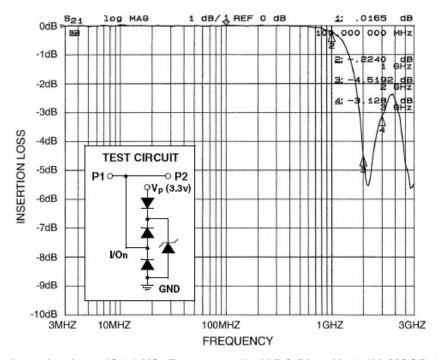


Figure 2. Insertion Loss (S21) VS. Frequency (2.5V DC Bias, V_P=3.3V, MSOP-8 Package)

Performance Information (Cont'd)

Typical Filter Performance (nominal conditions unless specified otherwise, 50 Ohm Environment)

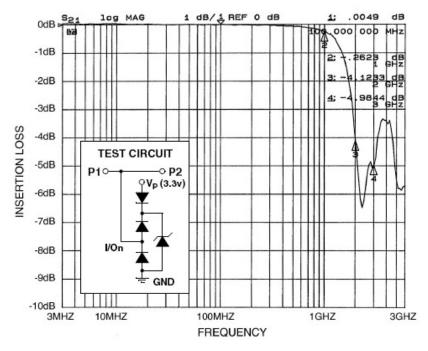


Figure 3. Insertion Loss (S21) VS. Frequency (0V DC Bias, V_p=3.3V, MSOP-10 Package)

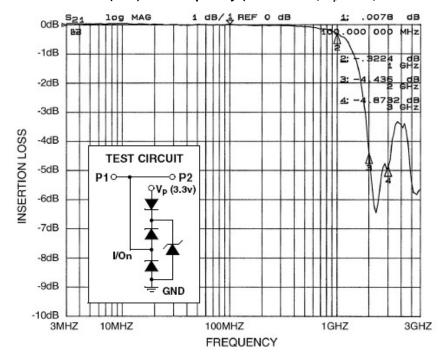


Figure 4. Insertion Loss (S21) VS. Frequency (2.5V DC Bias, V_P=3.3V)

CM1223

Backdrive Protection

Backdrive protection is needed to block against backdrive current flowing from a high potential voltage node toward a lower potential voltage node through the interface cable.

For example, consider a DVD player connected to a TV via an HDMI interface. If the DVD player is switched off and the TV is left on, there is a possibility of reverse current flow back into the main power supply rail of the DVD player. Typically, the DVD's power supply has some form of associated bulk supply capacitance, and it is possible over time to charge that bulk supply capacitance to some intermediate level.

If that level rises above the power-on-reset (POR) voltage level of some of the integrated circuits, the DVD player may not reset properly when the DVD player is turned back on. This is largely because all CMOS logic exhibits a very high impedance on the power rail node even when "off".

To avoid this situation, the CM1223 with integrated backdrive protection diode was designed to block backdrive current, guaranteeing no more than 5μ A on any I/O pin when the I/O pin voltage is greater than the CM1223 supply voltage.

Application Information

Design Considerations

To realize the maximum protection against ESD pulses, care must be taken in the PCB layout to minimize parasitic series inductances on the Supply/Ground rails as well as the signal trace segments between the signal input (typically a connector) and the ESD protection device. Application of Positive ESD Pulse between Input Channel and Ground illustrates an example of a positive 8kV ESD pulse striking an input channel. The 8kV ESD current pulse will divert along the path as indicated in Application of Positive ESD Pulse between Input Channel and Ground, through the D1 diode and the Zener diode back to the ground rail.

An ESD current pulse can rise from zero to its peak value in a very short time. For example, a level 4 contact discharge per the IEC61000-4-2 standard results in a current pulse that rises from zero to 30 Amps in 1ns. The CM1223 has a fast response time of less than 1ns and low clamp voltage to handle this pulse scenario.

Similarly for negative ESD pulses, parasitic series inductance from the V_N pin to the ground rail will lead to drastically increased negative voltage on the line being protected.

The CM1223 also has an integrated backdrive diode between $V_{_{P}}$ and $V_{_{N}}$ to prevent backdrive current flow from the powered sources.

As a general rule, the ESD Protection Array should be located as close as possible to the point of entry of expected electrostatic discharges.

Additional Information

See also California Micro Devices Application Note AP209, "Design Considerations for ESD Protection", in the Applications section at www.cmd.com.

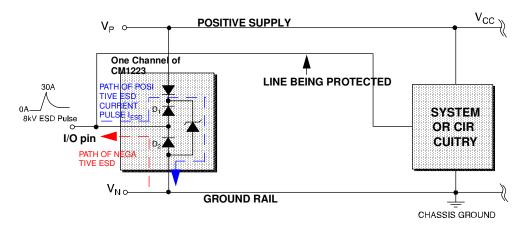


Figure 5. Application of Positive ESD Pulse between Input Channel and Ground

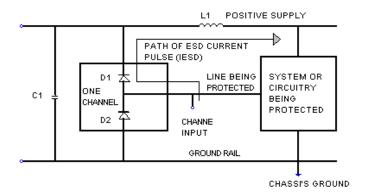


Figure 6. Application of Positive ESD Pulse between Input Channel and Ground

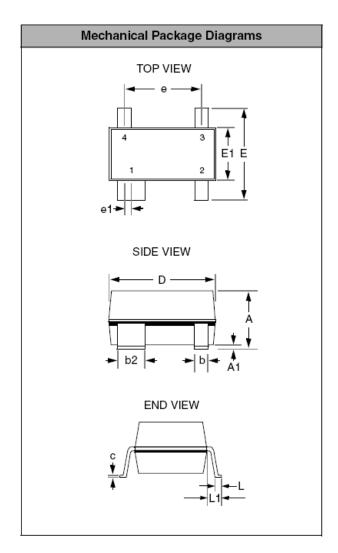
Mechanical Details

The CM1223 is available in SOT143-4, SOT23-5, SOT23-6, and MSOP-10 packages with a lad-free finishing option. The various package drawings are presented below.

SOT143 Mechanical Specifications

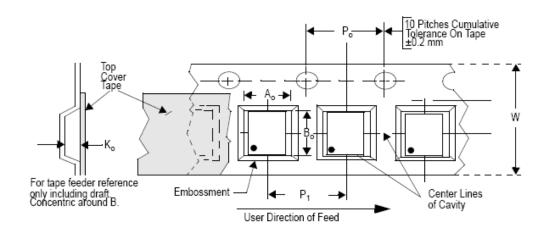
Dimensions for CM1223-02SR devices supplied in 4-pin SOT143 packages are presented below.

PACKAGE DIMENSIONS						
Package		SOT143				
Pins			4			
Dimensions	Millir	neters	Inc	ches		
	Min	Max	Min	Max		
Α	0.80	1.22	0.031	0.048		
A 1	0.05	0.15	0.002	0.006		
b	0.30	0.50	0.012	0.019		
b2	0.76	0.89	0.030	0.035		
С	0.08	0.20	0.003	0.008		
D	2.80	3.04	0.110	0.119		
E	2.10	2.64	0.082	0.103		
E1	1.20	1.40	0.047	0.055		
е	1.92	BSC	0.07	5 BSC		
e1	0.20	BSC	0.008 BS	С		
L	0.4	0.6	0.016	0.024		
L1	0.54	REF	0.021 RE	F		
# per tape and reel		3000	pieces			
Controlling dimension: millimeters						



Package Dimensions for SOT143

PART NUMBER	PACKAGE SIZE (mm)	POCKET SIZE (mm) B _o X A _o X K _o	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P _o	P ,
CM1223-02SR	2.92 X 2.37 X 1.01	2.60 X 3.15 X 1.20	8mm	178mm (7")	3000	4mm	4mm

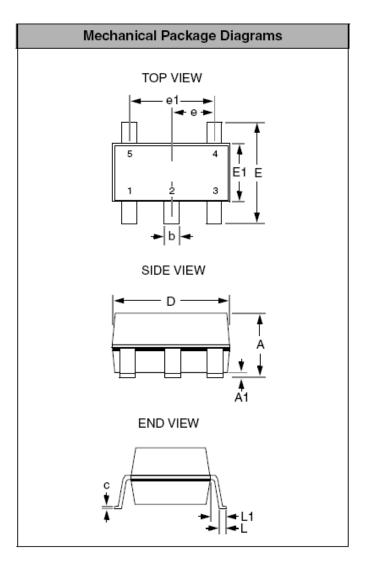


Mechanical Details (cont'd)

SOT23-5 Mechanical Specifications

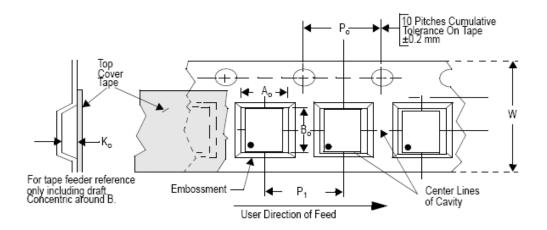
The CM1223-02SO is supplied in a 5-pin SOT23 package. Dimensions are presented below.

PACKAGE DIMENSIONS						
Package	SOT2	3-5 (JEDEC	name is M	IO-178)		
Pins			5			
Dimensions	Millir	neters	Inc	hes		
Dimensions	Min	Max	Min	Max		
Α	1	1.45		0.0571		
A 1	0.00	0.15	0.0000	0.0059		
b	0.30	0.50	0.0118	0.0197		
С	0.08	0.22	0.0031	0.0087		
D	2.75	3.05	0.1083	0.1201		
E	2.60	3.00	0.1024	0.1181		
E1	1.45	1.75	0.0571	0.0689		
е	0.95	BSC	0.037	4 BSC		
e1	1.90	BSC	0.074	8 BSC		
L	0.30	0.60	0.0118	0.0236		
L1	0.60	REF	0.0236 REF			
# per tape and reel	3000 pieces					
Controlling dimension: millimeters						



Package Dimensions for SOT23-5

PART NUMBER	PACKAGE SIZE (mm)	POCKET SIZE (mm) B _o X A _o X K _o	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P _o	P,
CM1223-02SO	2.90 X 2.80 X 1.45	3.20 X 3.20 X 1.40	8mm	178mm (7")	3000	4mm	4mm

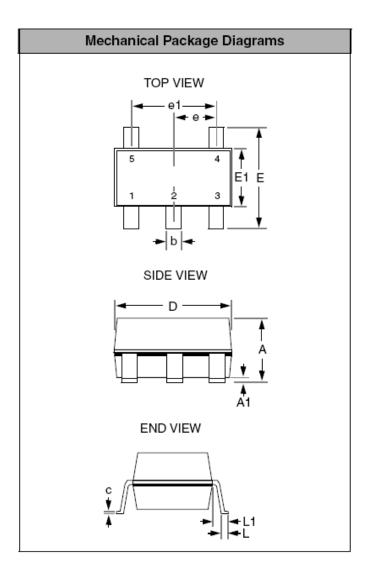


Mechanical Details (cont'd)

SOT23-6 Mechanical Specifications

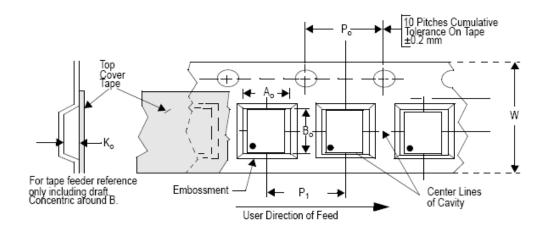
CM1223-04SO devices are packaged in 6-pin SOT23 packages. Dimensions are presented below.

PACKAGE DIMENSIONS						
Package	SOT2	3-6 (JEDEC	name is M	1 O-178)		
Pins		ı	6			
Dimensions	Millir	neters	Inc	hes		
Dimensions	Min	Max	Min	Max		
A		1.45		0.0571		
A 1	0.00	0.15	0.0000	0.0059		
b	0.30	0.50	0.0118	0.0197		
С	0.08	0.22	0.0031	0.0087		
D	2.75	3.05	0.1083	0.1201		
E	2.60	3.00	0.1024	0.1181		
E1	1.45	1.75	0.0571	0.0689		
е	0.95	BSC	0.037	'4 BSC		
e1	1.90	BSC	0.074	8 BSC		
L	0.30	0.60	0.0118	0.0236		
L1	0.60	REF	0.0236 REF			
# per tape and reel		3000	pieces			
С	Controlling dimension: millimeters					



Package Dimensions for SOT23-6

PART NUMBER	PACKAGE SIZE (mm)	POCKET SIZE (mm) B _o X A _o X K _o	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P _o	P ₁
CM1223-04SO	2.90 X 2.80 X 1.45	3.20 X 3.20 X 1.40	8mm	178mm (7")	3000	4mm	4mm

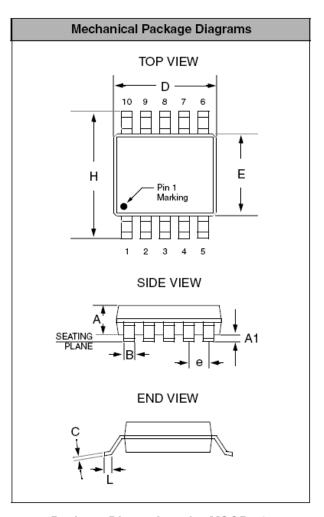


Mechanical Details (cont'd)

MSOP-10 Mechanical Specifications, 10 pin

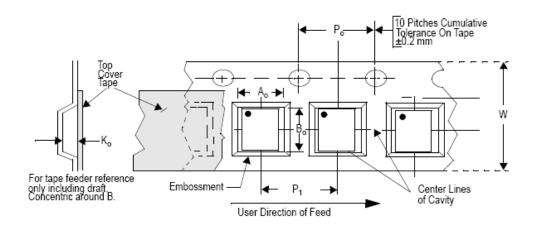
The CM1223-08MR 10-lead MSOP package dimensions are presented below.

PACKAGE DIMENSIONS										
Package	MSOP									
Pins	10									
Dimensions	Millir	neters	Inches							
	Min	Max	Min	Max						
Α	0.75	0.95	0.028	0.038						
A 1	0.05	0.15	0.002	0.006						
В	0.17	0.27	0.007	0.013						
С	0.13	0.23	0.005	0.009						
D	2.90	3.10	0.114	0.122						
E	2.90	3.10	0.114	0.122						
е	0.50 BSC		0.0196 BSC							
Н	4.90 BSC		0.193 BSC							
L	0.40	0.70	0.0137	0.029						
# per tape and reel	4000									
Controlling dimension: millimeters										



Package Dimensions for MSOP-10

PART NUMBER	PACKAGE SIZE (mm)	POCKET SIZE (mm) B _o X A _o X K _o	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P _o	P,
CM1223-08MR	3.00 X 3.00 X 0.85	3.30 X 5.30 X 1.30	12mm	330mm (13")	4000	4mm	8mm



CM1223

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